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RF360 Europe GmbH

A Qualcomm – TDK Joint Venture

## SAW Components

### SAW RF filter

Automotive telematics

Series/type:	B3517
Ordering code:	B39162B3517U510
Date:	January 30, 2013
Version:	2.3

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# SAW Components

## SAW RF filter

Automotive telematics

<b>Series/type:</b>	<b>B3517</b>
<b>Ordering code:</b>	<b>B39162B3517U510</b>
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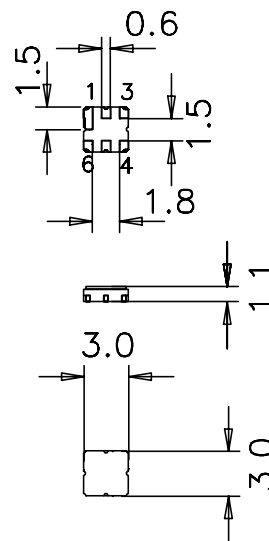
Data sheet


**Application**

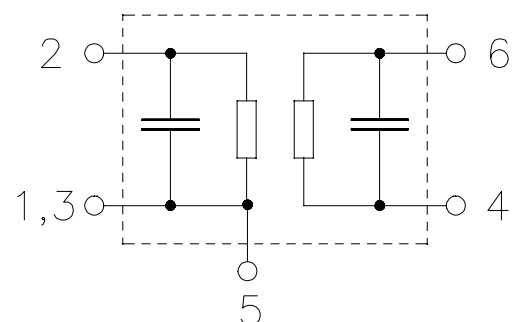
- Low-loss RF filter for automotive telematics applications
- Unbalanced to balanced operation
- Low insertion attenuation
- Low amplitude ripple
- Usable passband 42.0 MHz


**Features**

- Package size 3.0 x 3.0 x 1.1 mm<sup>3</sup>
- Package code DCC6D
- RoHS compatible
- Approximate weight 0.037 g
- Package for **Surface Mount Technology (SMT)**
- Ni, gold-plated terminals
- Lead free soldering compatible with J - STD20C
- **Electrostatic Sensitive Device (ESD)**


**Pin configuration**

- 2 Input unbalanced
- 4,6 Output balanced
- 1,3,5 Case ground (to be grounded)



Data sheet


**Characteristics**

Temperature range for specification:	T = -40 °C to +85 °C
Terminating source impedance:	Z <sub>S</sub> = 50 Ω
Terminating load impedance:	Z <sub>L</sub> = 100 Ω   18nH (balanced)

		min.	typ.	max.	
<b>Center frequency</b>	f <sub>C</sub>	—	1586	—	MHz
<b>Maximum insertion attenuation</b>	α <sub>max</sub>				
1565.0 ... 1607.0 MHz		—	1.9	2.5	dB
<b>Amplitude ripple (p-p)</b>	Δα				
1565.0 ... 1607.0 MHz		—	0.7	1.4	dB
<b>Input VSWR</b>					
1565.0 ... 1607.0 MHz		—	1.7	2.4	
<b>Output VSWR</b>					
1565.0 ... 1607.0 MHz		—	1.7	2.3	
<b>Group delay ripple<sup>1)</sup> (p-p)</b>					
1565.0 ... 1607.0 MHz		—	9	20	ns
1597.0 ... 1607.0 MHz		—	7	14	ns
<b>Attenuation</b>	α				
10.0 ... 960.0 MHz		52	57	—	dB
960.0 ... 1463.0 MHz		47	52	—	dB
1710.0 ... 1785.0 MHz		39	43	—	dB
1785.0 ... 1850.0 MHz		42	47	—	dB
1850.0 ... 1910.0 MHz		45	50	—	dB
1910.0 ... 2050.0 MHz		50	53	—	dB
2050.0 ... 2300.0 MHz		38	41	—	dB
2300.0 ... 2400.0 MHz		45	55	—	dB
2400.0 ... 2500.0 MHz		53	57	—	dB

1) Averaged over 500 kHz

Data sheet


**Characteristics**

Temperature range for specification:	T = -40 °C to +125 °C
Terminating source impedance:	Z <sub>S</sub> = 50 Ω
Terminating load impedance:	Z <sub>L</sub> = 100 Ω    18 nH (balanced)

		min.	typ.	max.	
<b>Center frequency</b>	f <sub>C</sub>	—	1586	—	MHz
<b>Maximum insertion attenuation</b>	α <sub>max</sub>				
1565.0 ... 1607.0 MHz		—	1.9	2.7	dB
<b>Amplitude ripple (p-p)</b>	Δα				
1565.0 ... 1607.0 MHz		—	0.7	1.6	dB
<b>Input VSWR</b>					
1565.0 ... 1607.0 MHz		—	1.7	2.4	
<b>Output VSWR</b>					
1565.0 ... 1607.0 MHz		—	1.7	2.4	
<b>Group delay ripple<sup>1)</sup> (p-p)</b>					
1565.0 ... 1607.0 MHz		—	9	22	ns
1597.0 ... 1607.0 MHz		—	7	16	ns
<b>Attenuation</b>	α				
10.0 ... 960.0 MHz		52	57	—	dB
960.0 ... 1463.0 MHz		42	52	—	dB
1710.0 ... 1785.0 MHz		39	43	—	dB
1785.0 ... 1850.0 MHz		42	47	—	dB
1850.0 ... 1910.0 MHz		45	50	—	dB
1910.0 ... 2050.0 MHz		50	53	—	dB
2050.0 ... 2300.0 MHz		38	41	—	dB
2300.0 ... 2400.0 MHz		45	55	—	dB
2400.0 ... 2500.0 MHz		53	57	—	dB

1) Averaged over 500 kHz


**Maximum ratings**

Operable temperature range	T	-45/+125	°C	
Storage temperature range	T <sub>stg</sub>	-45/+125	°C	
DC voltage	V <sub>DC</sub>	6	V	
ESD voltage	V <sub>ESD</sub>	50 <sup>1)</sup>	V	machine model, 10 pulses
Input power at				source 50Ω, load 100Ω    18nH
1565.0 ... 1607.0 MHz	P <sub>IN</sub>	5	dBm	cw
2400 ... 2483.5 MHz	P <sub>IN</sub>	20	dBm	cw
824...960, 1710...2170 MHz	P <sub>IN</sub>	20	dBm	cw
960...1525 MHz	P <sub>IN</sub>	10	dBm	cw

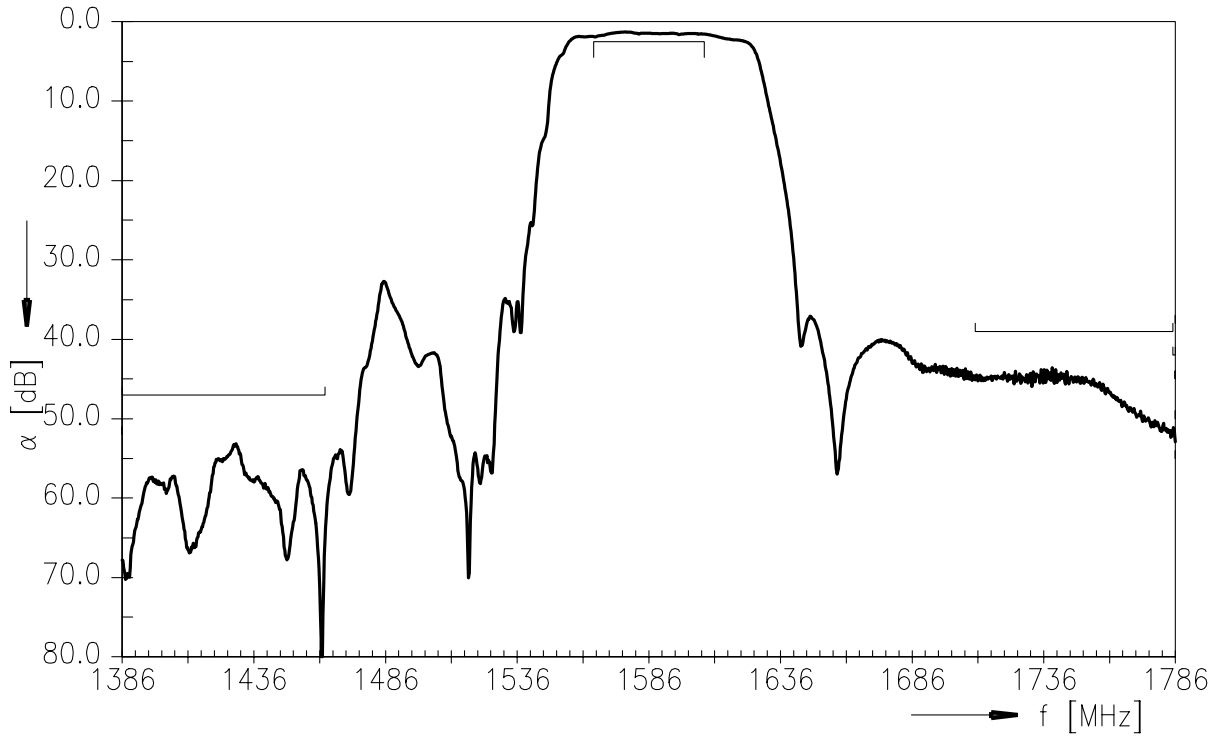
<sup>1)</sup> acc. to JESD22-A115A (machine model), 10 negative & 10 positive pulses.



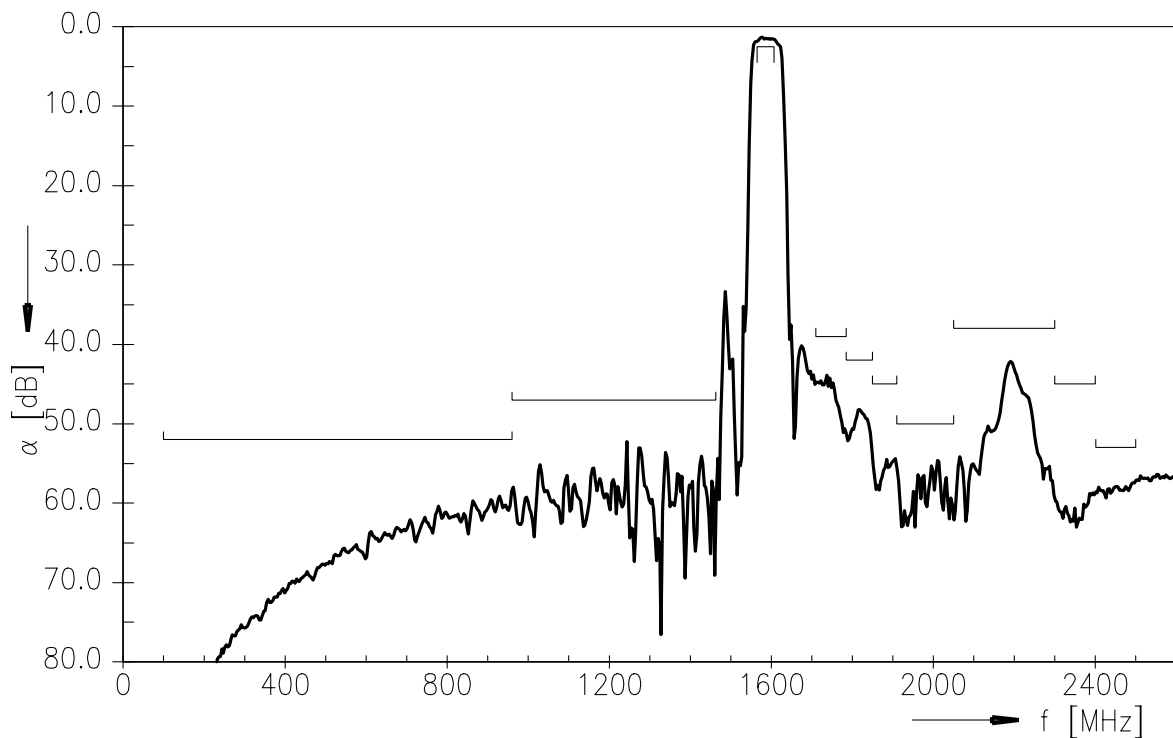
Data sheet



**Transfer function**

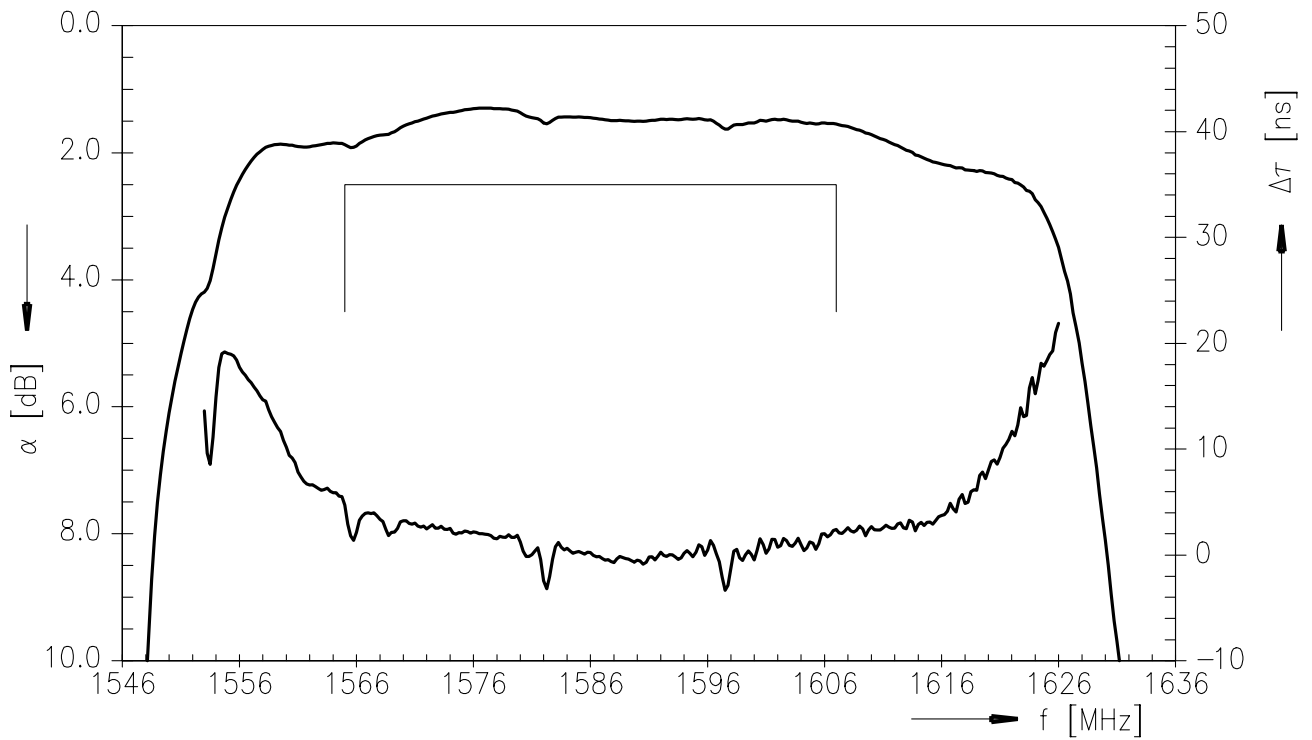


**Transfer function (wideband)**





Group delay time





### ESD protection of SAW filters

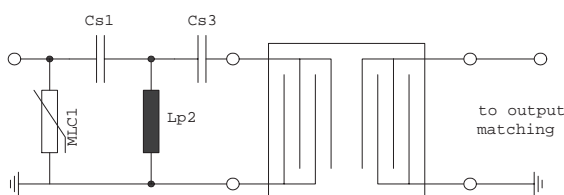
SAW filters are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, “ESD matching” has to be ensured at that filter port, where electrostatic discharge is expected.

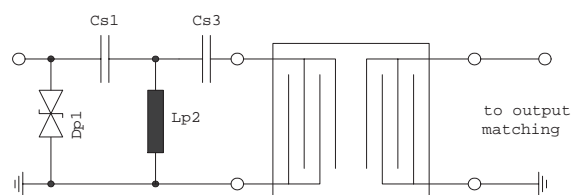
Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wideband filters the high-pass ESD matching structure needs to be at least of 3<sup>rd</sup> order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.

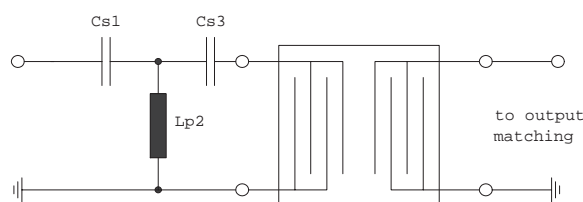


**Fig. 1 MLC varistor plus ESD matching**



**Fig. 2 Suppressor diode plus ESD matching**

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.



**Fig. 3 3<sup>rd</sup> order high-pass structure for basic ESD protection**

In all three figures the shunt inductor Lp2 could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available pcb space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements

For further information, please refer to EPCOS Application report:

**“ESD protection for SAW filters”.**

This report can be found under [www.epcos.com/rke](http://www.epcos.com/rke). Click on “Applications Notes”.

Data sheet


**References**

<b>Type</b>	B3517
<b>Ordering code</b>	B39162B3517U510
<b>Marking and package</b>	C61157-A7-A68
<b>Packaging</b>	F61074-V8228-Z000
<b>Date codes</b>	L_1126
<b>S-parameters</b>	B3517_NB.s3p, B3517_WB.s3p see file header for port/pin assignment table
<b>Soldering profile</b>	S_6001
<b>RoHS compatible</b>	RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8 <sup>th</sup> , 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.
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**Published by EPCOS AG**  
**Systems, Acoustics, Waves Business Group**  
**P.O. Box 80 17 09, 81617 Munich, GERMANY**

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